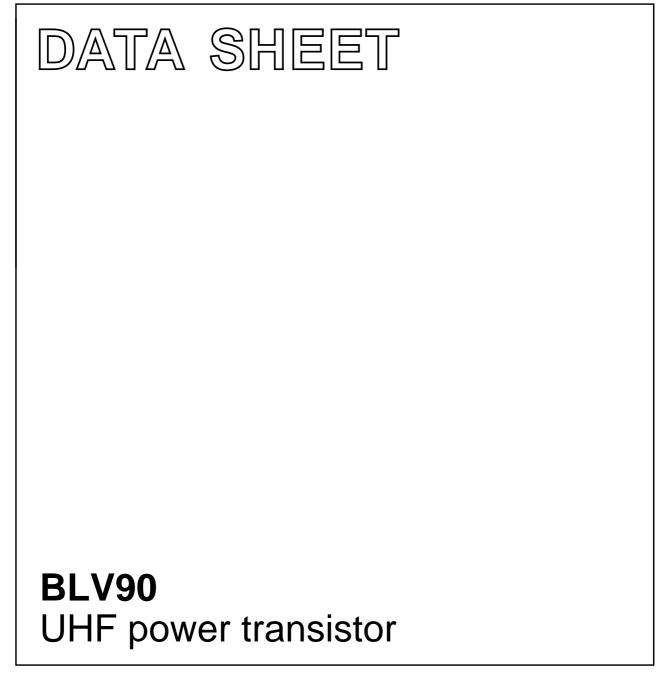
DISCRETE SEMICONDUCTORS



Product specification

February 1996



HILIPS

## BLV90

#### DESCRIPTION

NPN silicon planar epitaxial transistor designed for use in mobile radio transmitters in the 900 MHz band.

#### FEATURES

- diffused emitter-ballasting resistors for an optimum temperature profile.
- gold metallization ensures excellent reliability.
- the device can be applied at rated output power without an external heatsink when it is mounted on a printed-circuit board (see Fig.6).

The transistor has a 4-lead envelope with a ceramic cap (SOT-172D). All leads are isolated from the mounting base.

### QUICK REFERENCE DATA

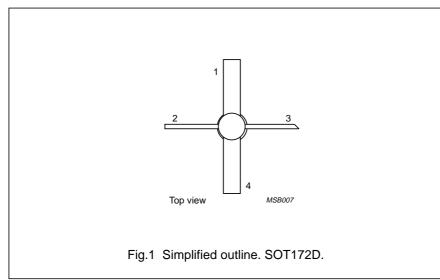
RF performance at  $T_a = 25$  °C in a common-emitter class-B circuit.<sup>(1)</sup>

MODE OF OPERATION	V <sub>CE</sub> V	f MHz	PL W	G <sub>p</sub> dB	າc %
Narrow band; CW	12.5	900	1	> 7.5	> 50
	9.6	900	1	typ. 7.0	typ. 57

#### Note

1. Device mounted on a printed-circuit board (see Fig.6).

#### PIN CONFIGURATION



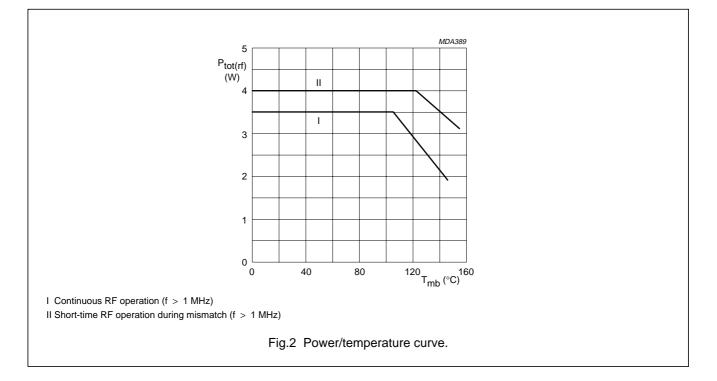
PRODUCT SAFETY This device incorporates beryllium oxide, the dust of which is toxic. The device is entirely safe provided that the BeO disc is not damaged.

#### PINNING - SOT172D.

PIN	DESCRIPTION		
1	emitter		
2	base		
3	collector		
4	emitter		

## BLV90

Limiting values in accordance with the Absolute Maximum Syste	m (IEC 134)			
Collector-base voltage (open emitter)	V <sub>CBO</sub>	max.	36	V
Collector-emitter voltage (open base)	V <sub>CEO</sub>	max.	16	V
Emitter-base voltage (open collector)	V <sub>EBO</sub>	max.	3	V
Collector current				
DC or average	I <sub>C</sub> ; I <sub>C(AV)</sub>	max.	0.2	А
(peak value); f > 1 MHz	I <sub>CM</sub>	max.	0.6	А
Total power dissipation				
f > 1 MHz; T <sub>mb</sub> < 105 °C	P <sub>tot(rf)</sub>	max.	3.5	W
Storage temperature	T <sub>stg</sub>	-65 to -	+ 150	°C
Operating junction temperature	Тj	max.	200	°C



#### THERMAL RESISTANCE

Dissipation = 2.25 W				
From junction to $ambient^{(1)}$ (f > 1 MHz)				
$T_a = 25 \text{ °C}$	R <sub>th j–a (RF)</sub>	max.	60	K/W
From junction to mounting base				
T <sub>mb</sub> = 25 °C (f > 1 MHz)	R <sub>th j-mb (RF)</sub>	max.	19	K/W

#### Note

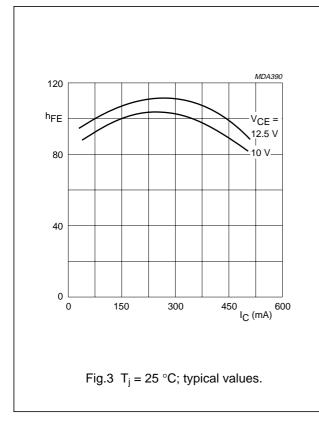
1. Device mounted on a printed-circuit board (see Fig.6).

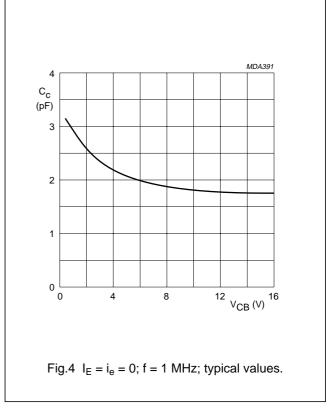
**CHARACTERISTICS** 

# UHF power transistor

# BLV90

$T_j = 25 \ ^{\circ}C$ unless otherwise specified				
Collector-base breakdown voltage				
open emitter; $I_C = 2.5 \text{ mA}$	V <sub>(BR)CBO</sub>	>	36	V
Collector-emitter breakdown voltage				
open base; I <sub>C</sub> = 10 mA	V <sub>(BR)CEO</sub>	>	16	V
Emitter-base breakdown voltage				
open collector; I <sub>E</sub> = 0.5 mA	V <sub>(BR)EBO</sub>	>	3	V
Collector cut-off current				
$V_{BE} = 0; V_{CE} = 16 V$	I <sub>CES</sub>	<	1	mA
Second breakdown energy				
L = 25 mH; f = 50 Hz; $R_{BE}$ = 10 $\Omega$	E <sub>SBR</sub>	>	0.3	mJ
D.C. current gain				
$I_{C} = 0.15 \text{ A}; V_{CE} = 10 \text{ V}$	h <sub>FE</sub>	>	25	
Collector capacitance at f = 1 MHz				
I <sub>E</sub> = i <sub>e</sub> = 0; V <sub>CB</sub> = 12.5 V	C <sub>c</sub>	typ.	1.8	pF
Feedback capacitance at f = 1 MHz				
$I_{C} = 0; V_{CE} = 12.5 V$	C <sub>re</sub>	typ.	1.0	pF
Collector-mounting base capacitance	C <sub>c-mb</sub>	typ.	0.5	pF



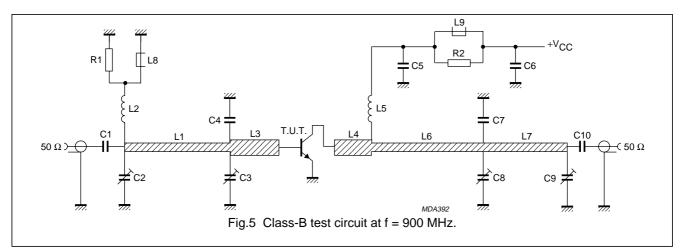


BLV90

### **APPLICATION INFORMATION**

RF performance in CW operation (common-emitter circuit, class-B): f = 900 MHz; T<sub>a</sub> = 25 °C

MODE OF OPERATION	V <sub>CE</sub> V	P <sub>L</sub> W	G <sub>p</sub> dB	<sup>ղ</sup> c %
narrow band; CW	12.5	1	> 7.5	> 50
			typ. 9.0	typ. 60
	9.6	1	typ. 7.0	typ. 57



List of components:

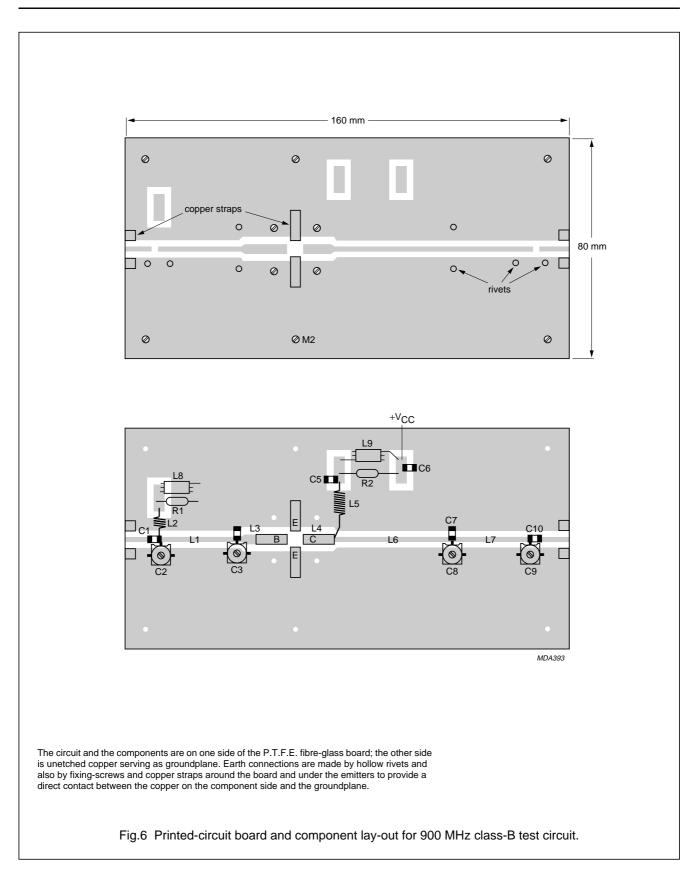
- C1 = C10 = 33 pF multilayer ceramic chip capacitor
- C2 = C9 = 1.4 to 5.5 pF film dielectric trimmer (cat. no. 2222 809 09001)
- C3 = 2 to 9 pF film dielectric trimmer (cat. no. 2222 809 09002)
- C4 = 5.6 pF multilayer ceramic chip capacitor<sup>(1)</sup>
- C5 = 10 pF multilayer ceramic chip capacitor
- C6 = 330 pF multilayer ceramic chip capacitor
- C7 = 3.9 pF multilayer ceramic chip capacitor<sup>(1)</sup>
- C8 = 1.2 to 3.5 pF film dielectric trimmer (cat. no. 2222 809 05001)
- L1 = L7 = 50  $\Omega$  stripline (30.8 mm  $\times$  2.4 mm)
- L2 = 60 nH; 4 turns closely wound enamelled Cu wire (0.4 mm); int. dia. 3 mm; leads 2 × 5 mm
- L3 =  $38 \Omega$  stripline (16.0 mm  $\times$  3.5 mm)
- L4 =  $38 \Omega$  stripline (11.0 mm  $\times$  3.5 mm)
- L5 = 280 nH; 15 turns closely wound enamelled Cu wire (0.4 mm); int. dia. 3 mm; leads 2 × 5 mm
- L6 =  $50 \Omega$  stripline (41.2 mm  $\times$  2.4 mm)
- L8 = L9 = Ferroxcube wideband HF choke, grade 3B (cat. no. 4312 020 36642)
- R1 = R2 = 10  $\Omega \pm 5\%$ ; 0.25 W metal film resistor
- L1, L3, L4, L6 and L7 are striplines on a double Cu-clad printed-circuit board with P.T.F.E. fibre-glass dielectric
- ( $\epsilon_r$  = 2.2); thickness <sup>1</sup>/<sub>32</sub> inch; thickness of copper-sheet 2 × 35 µm.

#### Notes

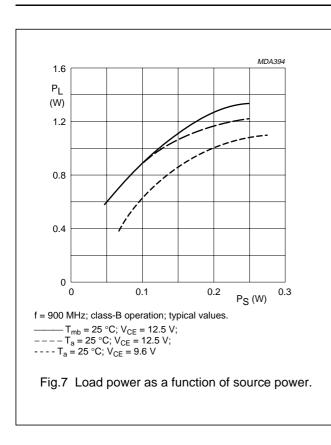
- 1. American Technical Ceramics capacitor type 100A or capacitor of same quality.
- 2. Device mounted on a printed-circuit board (see Fig.6).

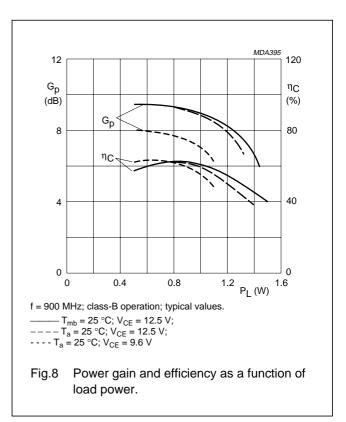
February 1996

## BLV90



# BLV90

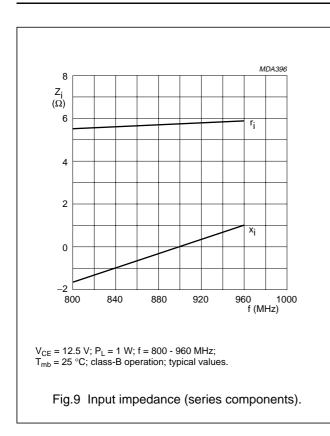


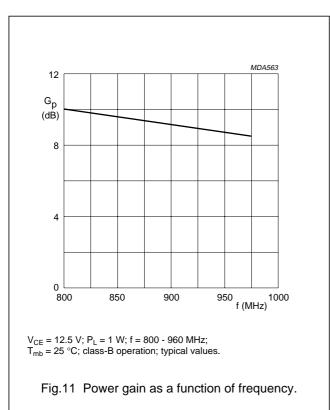


### RUGGEDNESS

The device is capable to withstand a full load mismatch (VSWR = 50; all phases) at rated load power up to a supply voltage of 15.5 V at  $T_a = 25$  °C. Device mounted on a printed-circuit board (see Fig.6).







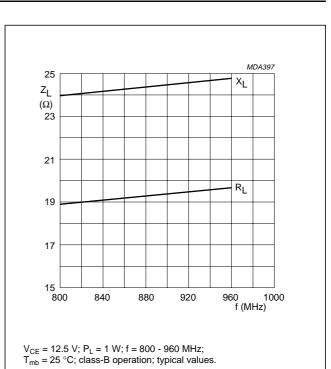
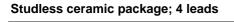
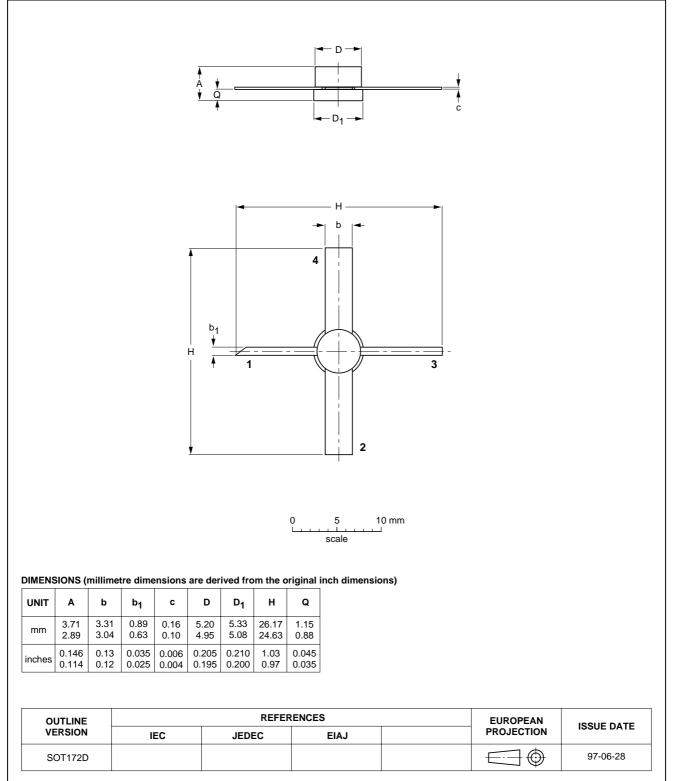


Fig.10 Load impedance (series components).

### PACKAGE OUTLINE





BLV90

#### SOT172D

Product specification

BLV90

#### DEFINITIONS

Data Sheet Status			
Objective specification	This data sheet contains target or goal specifications for product development.		
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.		
Product specification	This data sheet contains final product specifications.		
Limiting values			
more of the limiting values n of the device at these or at a	accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or nay cause permanent damage to the device. These are stress ratings only and operation any other conditions above those given in the Characteristics sections of the specification imiting values for extended periods may affect device reliability.		

### Application information

Where application information is given, it is advisory and does not form part of the specification.

#### LIFE SUPPORT APPLICATIONS

These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.